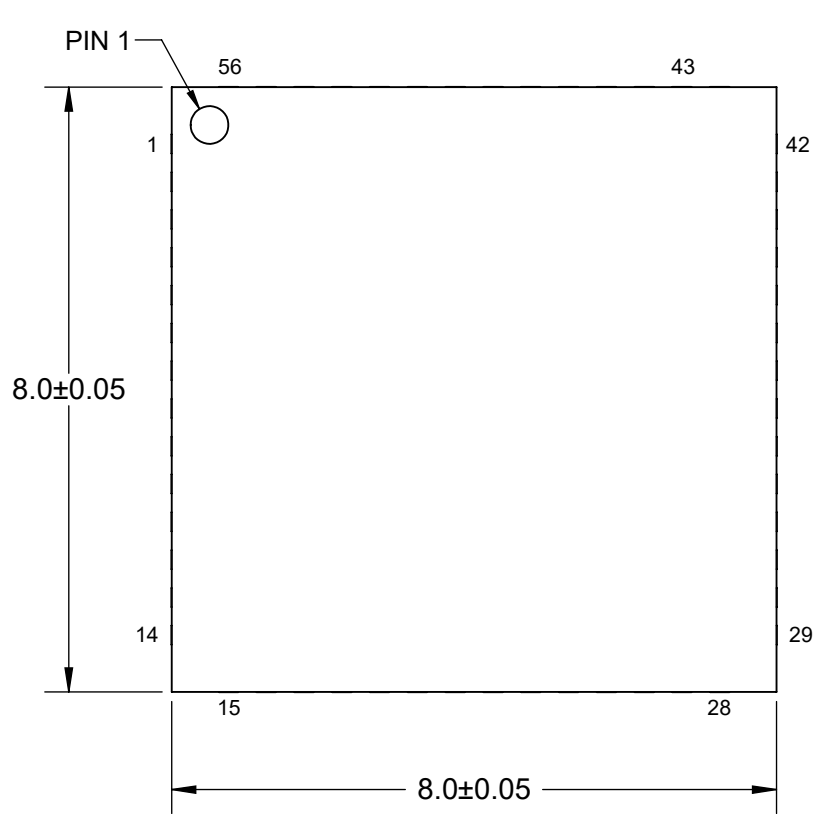
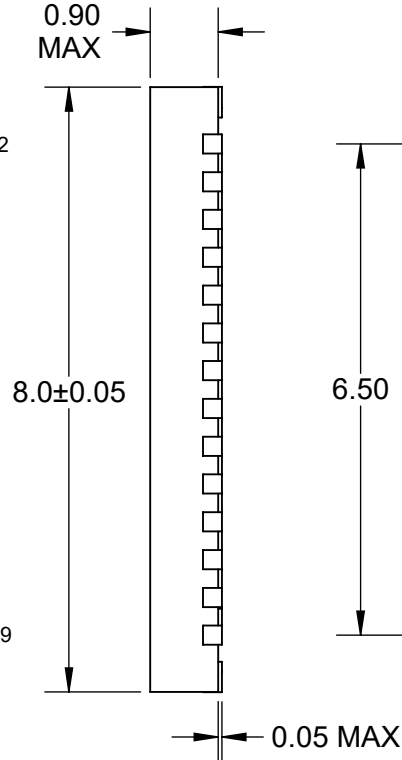


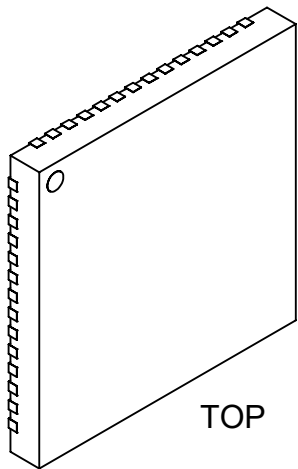
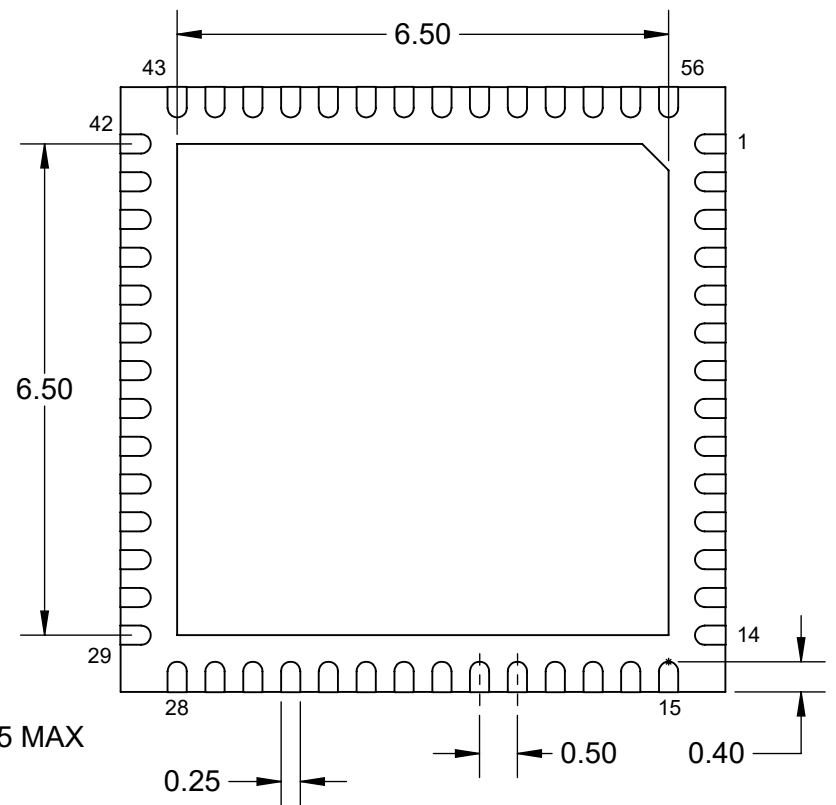
TOP VIEW



SIDE VIEW

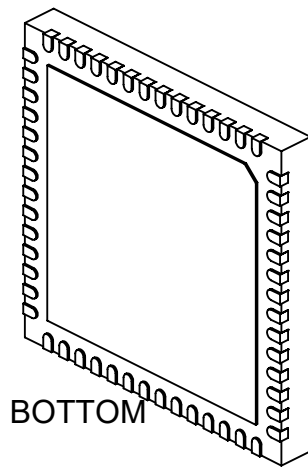


BOTTOM VIEW



TOP

MODEL



BOTTOM

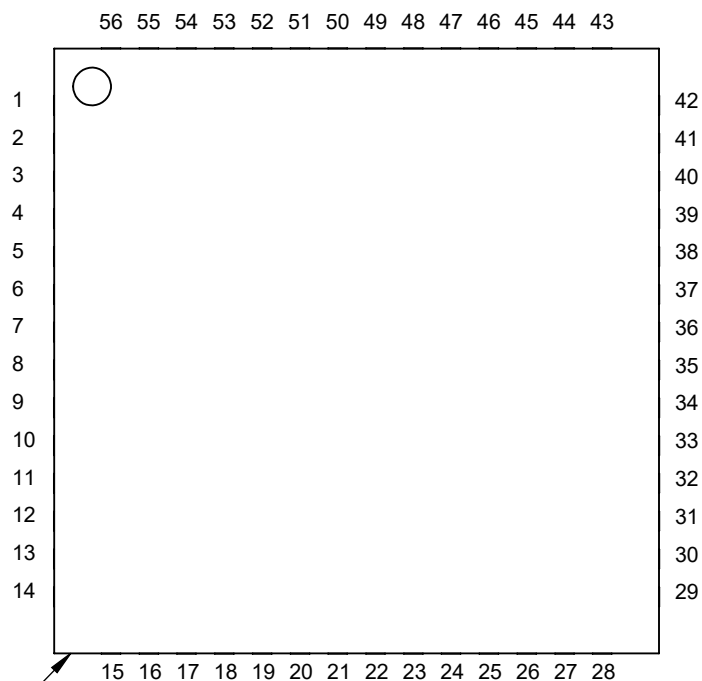
Notes: (Unless Otherwise Specified).

- 1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
- 2) LEAD FRAME: COPPER, C-194 F/H.
- 3) LEAD FRAME PLATING: NiPdAu.
- 4) FRAME THICKNESS: 0.203mm.
- 5) DIE PAD: 6.5 x 6.5mm EXPOSED BOTTOM.
- 6) JEDEC OUTLINE: MO-220.
- 7) DIMENSIONS IN mm.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	4/12/2020				
ENG M. Hart	4/12/2020	TITLE 56-LEAD 8mm P0.5mm QFN ISOLATED			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	455642	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

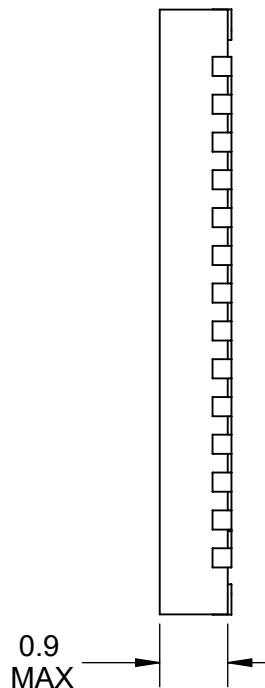
ISOLATED COMPONENT PAD PATTERN

TOP VIEW

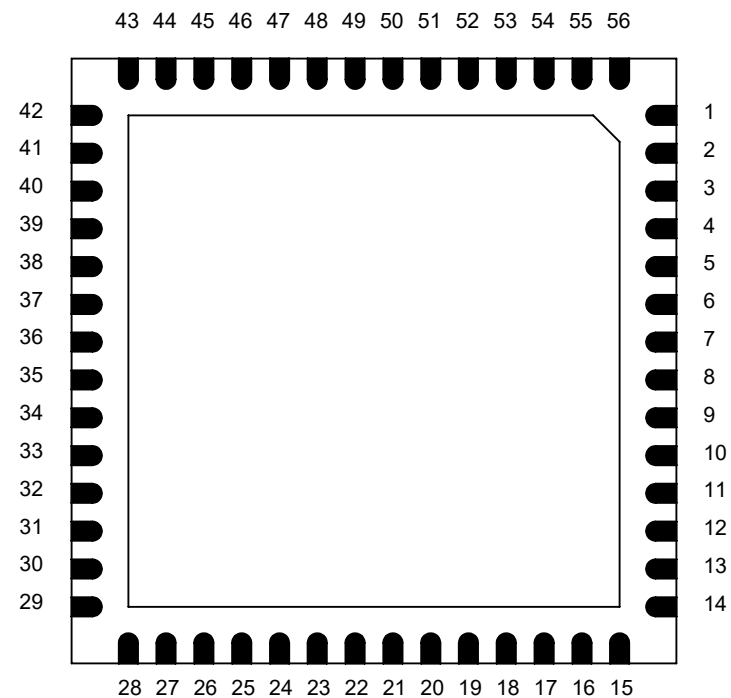


TOP SIDE ENCAPSULATION

SIDE VIEW



BOTTOM VIEW



NOTE:
1. PACKAGE IS FULLY ISOLATED (-ISO) TO INTERNAL BOND PADS.

TopLine®

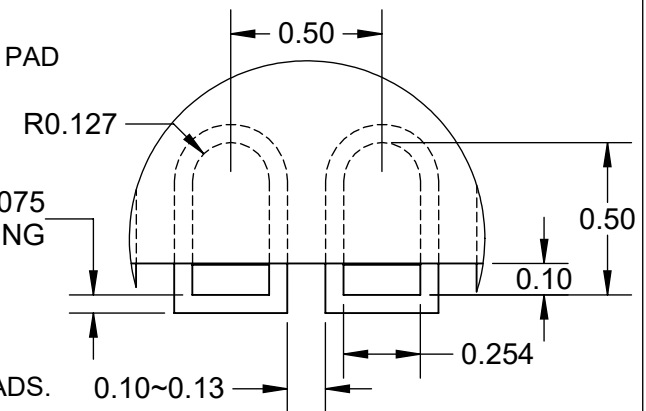
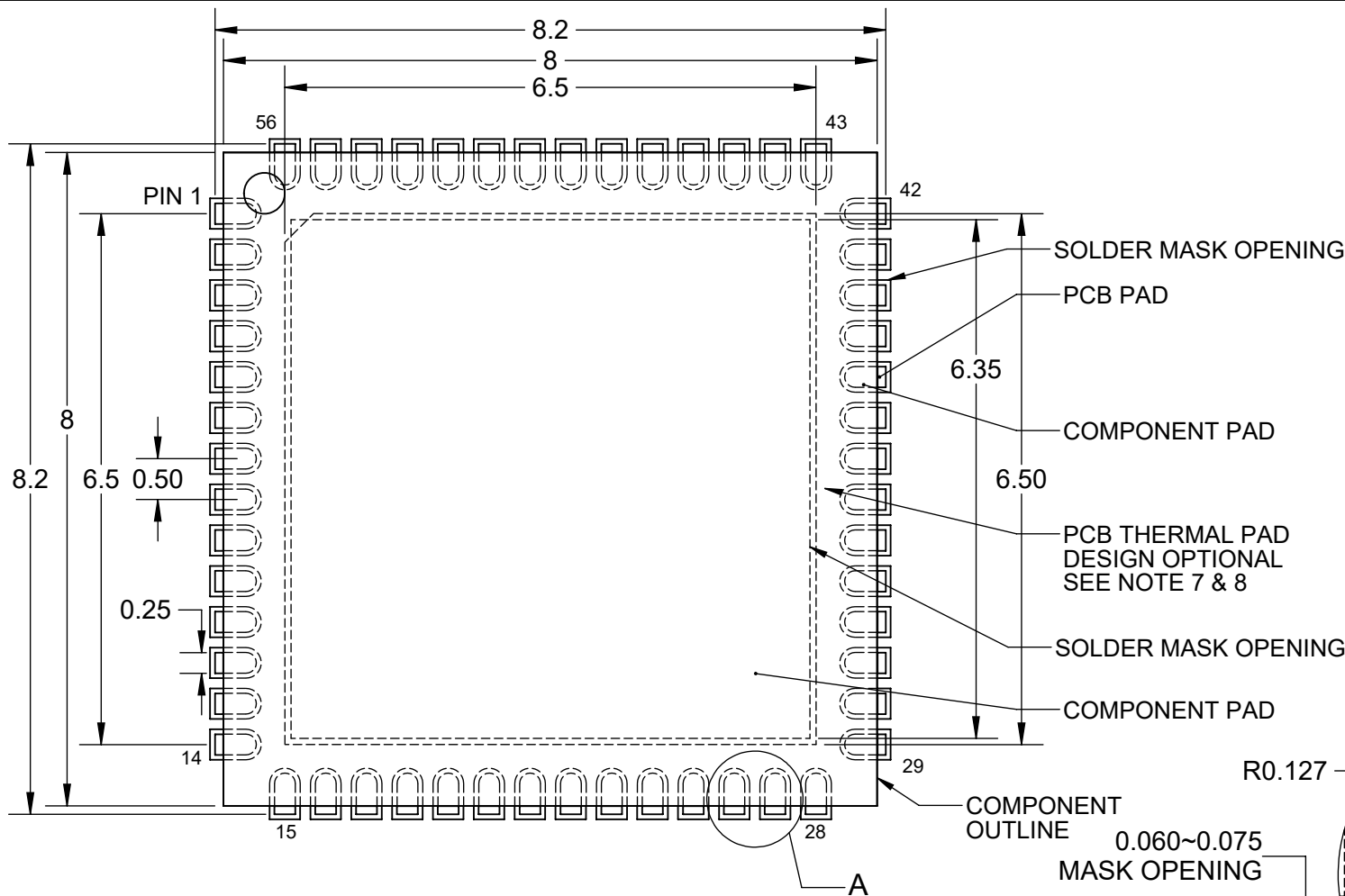
TITLE 56-LEAD 8mm P0.5mm
QFN ISOLATED

SCALE 10:1	SIZE A	DRAWING NO. 455642	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 4

PC BOARD LAYOUT DIMENSIONS IN MM VIEW FROM TOP



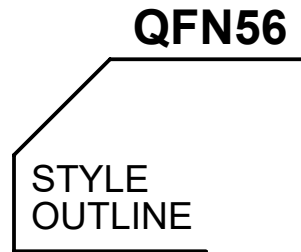
DETAIL A
SCALE 40 : 1

Notes: (Unless Otherwise Specified).

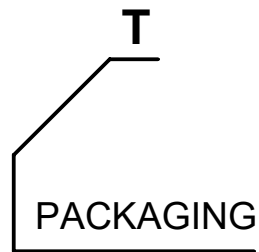
- 1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
- 2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
- 3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
- 4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
- 5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
- 6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
- 7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
 - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
 - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
 - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18 μ m).
 - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
- 8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
 - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
 - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERTURES INSTEAD OF ONE LARGE APERTURE TO CONTROL PASTE AMOUNTS.
 - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

TopLine®			
TITLE 56-LEAD 8mm P0.5mm QFN ISOLATED			
SCALE 8:1	SIZE A	DRAWING NO. 455642	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 4

PART NUMBERING SYSTEM



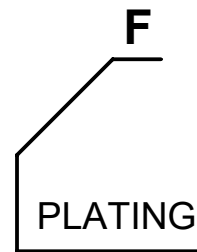
QUAD FLAT
NO LEAD
56-LEADS



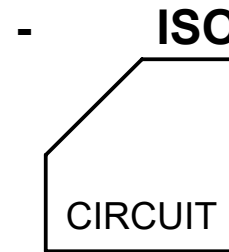
M = TUBE
T = TRAY
E = CUT TAPE
E7A = 7" REEL
E13A = 13" REEL



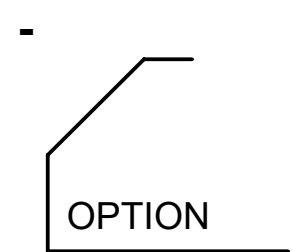
.5 = 0.5MM



F = Ni Pd Au



ISO = ISOLATED



BLANK = WITHOUT DIE
D = DUMMY DIE

PART NUMBER	DAISY CHAIN	ISOLATED	PACKAGING	RoHS Pb-FREE	MSL LEVEL	DUMMY DIE
QFN56T.5-F-ISO	NO	YES	JEDEC TRAY	YES	1	NO
QFN56E7A.5-F-ISO	NO	YES	TAPE & REEL	YES	1	NO

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

TopLine®			
TITLE 56-LEAD 8mm P0.5mm QFN ISOLATED			
SCALE NONE	SIZE A	DRAWING NO. 455642	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 4